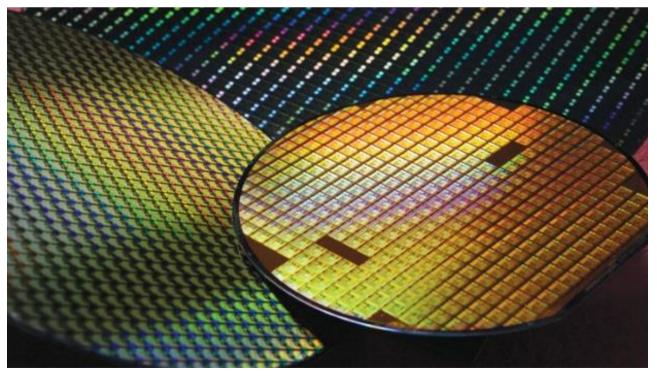
MSE 160 – Semiconductor characterization



Outline

Semiconductor wafer synthesis

Semiconductor resistivity measurement

Final presentation Q & A

62

Modern computers use single crystal Si wafer substrates



Monocrystalline

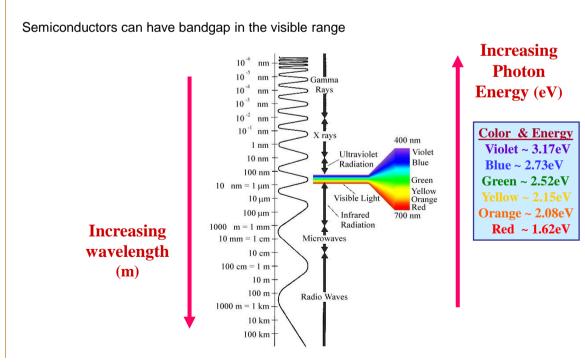
Modern computers use single crystal Si wafer substrates



Why is Si black?

Monocrystalline

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Home » Science & Innovation » Energy Sources » Solar

The tremendous growth in the U.S. solar industry is helping to pave the way to a cleaner, more sustainable energy future. Over the past few years, the cost of a solar energy system has dropped significantly -- helping to give more American families and business access to affordable, clean energy.

Through a portfolio of R&D efforts, the Energy Department remains committed to leveraging America's abundant solar energy resources -- driving research, manufacturing and market solutions to support widespread expansion of the nation's solar market.

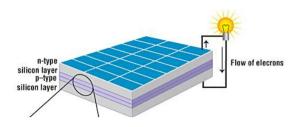
Solar Energy Technologies Office Solar Energy Technologies Office Homepage © VIEW MORE



66



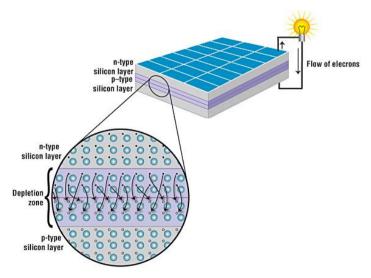
A photovoltaic cell is a p-n junction



Anthony Fernandez "How a Solar Cell Works" American Chemical Society, acs.org

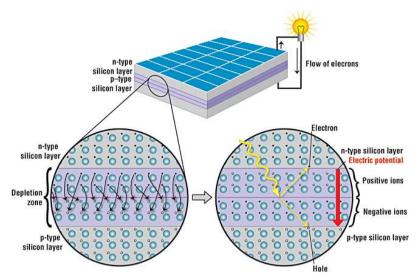
68

A photovoltaic cell is a p-n junction

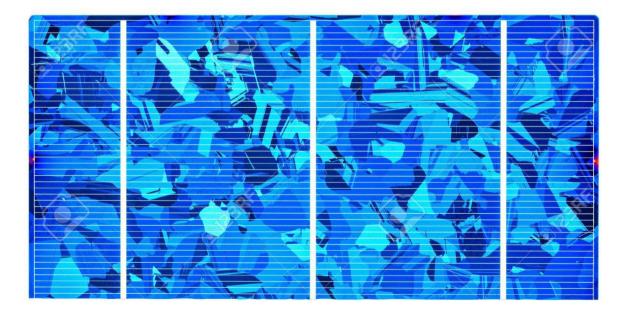


Anthony Fernandez "How a Solar Cell Works" American Chemical Society, acs.org

A photovoltaic cell is a p-n junction

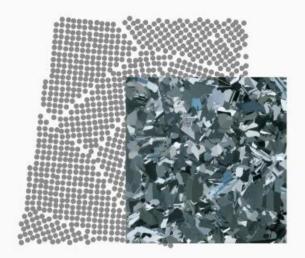


Anthony Fernandez "How a Solar Cell Works" American Chemical Society, acs.org



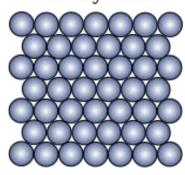


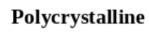
Monocrystalline

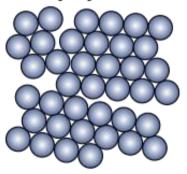


Multicrystalline

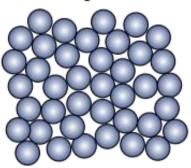
Monocrystalline





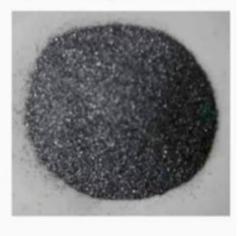


Amorphous



Si manufacturing is grounded in materials synthesis

Metallurgical silicon



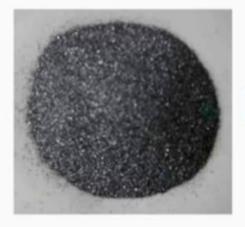
70% of mg-si is for Al alloying for automotive.30% for other Si for e.g. silicones.1% for poly and mono Si

Solar Energy - DelftX - Arno Smets

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Si manufacturing is grounded in materials synthesis

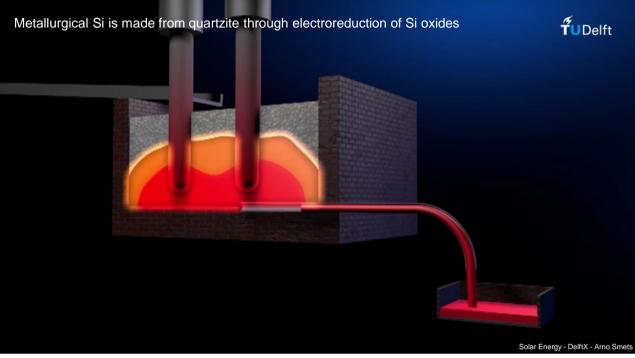
Metallurgical silicon



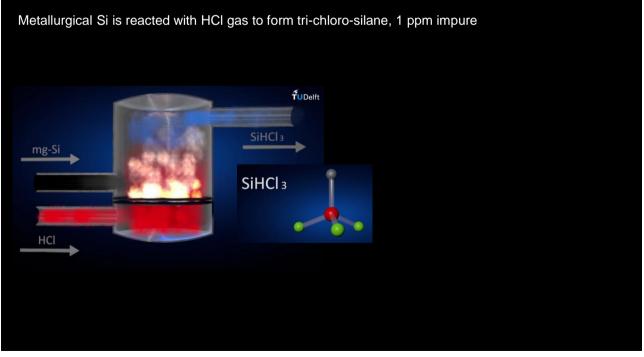


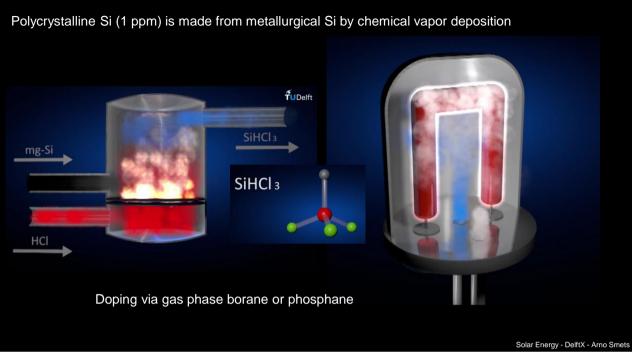


Solar Energy - DelftX - Arno Smets

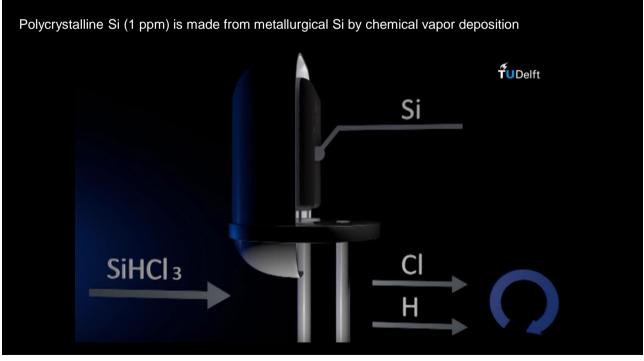












Modern computers use single crystal Si wafer substrates

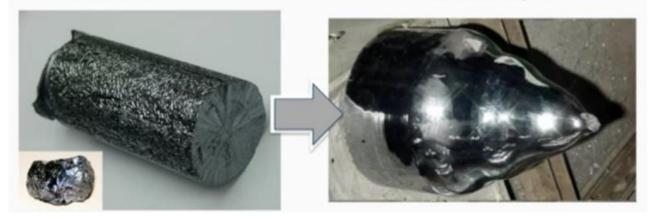


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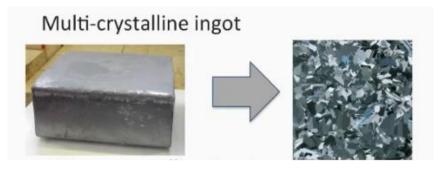
Si ingot is prepared from poly Si

Poly-silicon

Silicon Ingot

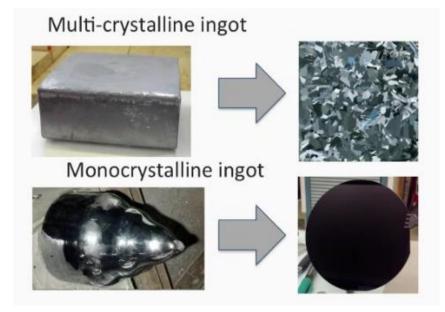


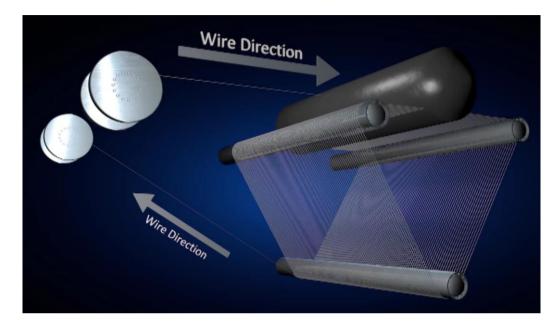
https://www.youtube.com/watch?v=8QKzS_w_ Ko0&t=320s Multicrystalline ingot is also produced from melt by directional solidification



82

Multicrystalline ingot is produced from melt

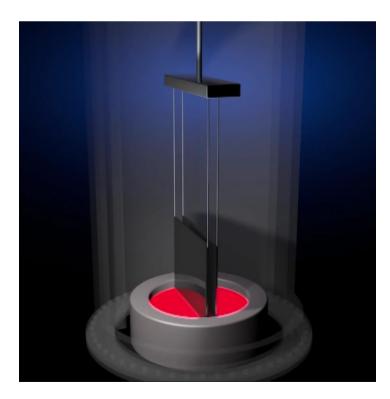




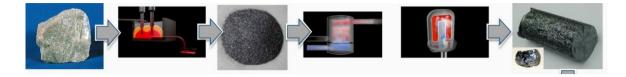
Wafers are created from ingot via sawing to ~150 μm

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Wafers are created from Si ribbon



Si manufacturing is grounded in materials synthesis



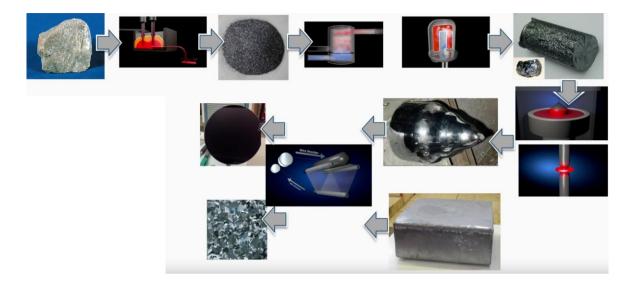
Solar Energy - DelftX - Arno Smets

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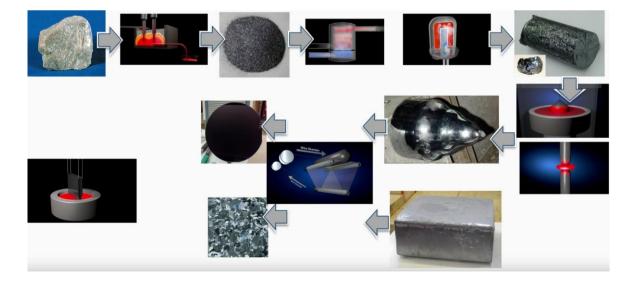
Si manufacturing is grounded in materials synthesis



Si manufacturing is grounded in materials synthesis



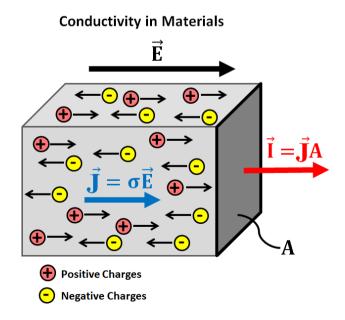
Si manufacturing is grounded in materials synthesis



How does this differ from metal? What happens in metals as T increases?

90

Conductivity of semiconductor increases with temperature



- Electrical conductivity, $\sigma = 1/\rho = \sum_{i} (nq\mu)_i$
- *i* = carrier (e.g. electron, hole, ion)
- n = carrier concentration
- q = carrier charge
- µ = carrier mobility

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Conductivity of semiconductor increases with temperature

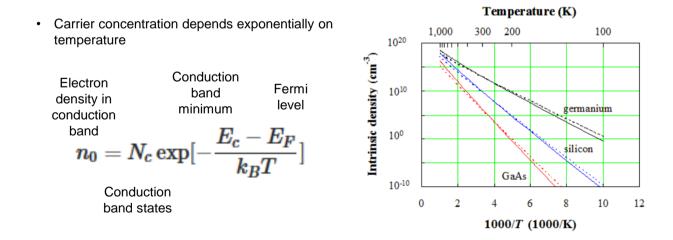
- Electrical conductivity, $\sigma = 1/\rho = \sum_{i} (nq\mu)_{i}$
- *i* = carrier (e.g. electron, hole, ion)
- n = carrier concentration
- q = carrier charge
- µ = carrier mobility
- With increasing temperature
 - q does not change
 - µ decreases (because of drift velocity)
 - n increases exponentially

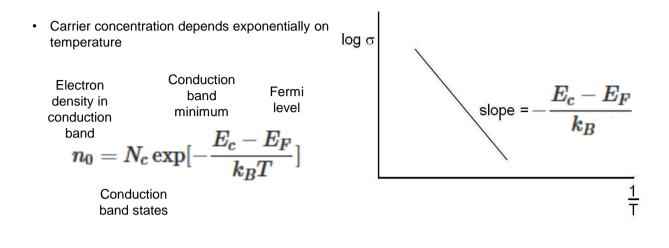
- Carrier concentration depends exponentially on temperature
 - Electron Conduction band Fermi level $n_0 = N_c \exp[-rac{E_c E_F}{k_B T}]$

Conduction band states

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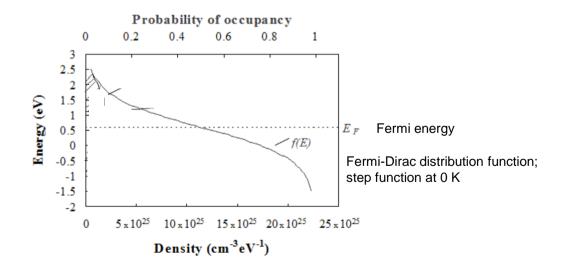
Conductivity of semiconductor increases with temperature

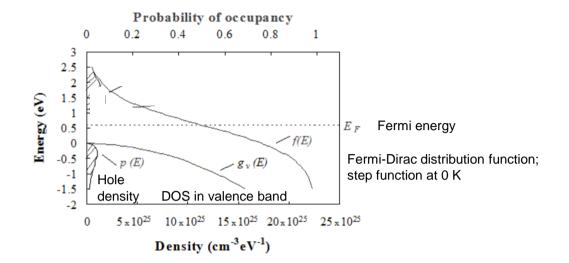




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Calculation of the electron and hole density in a semiconductor

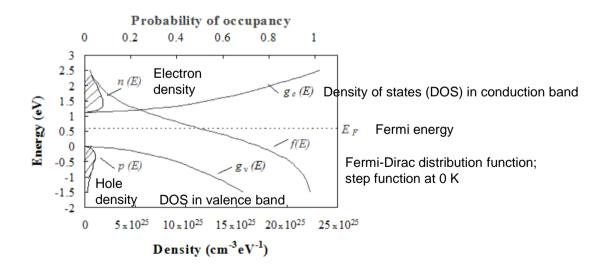


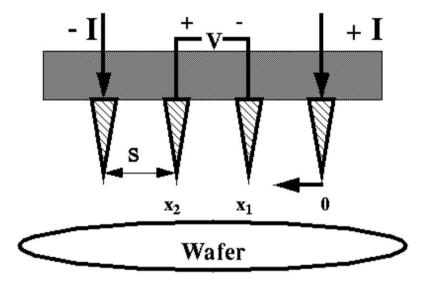


Calculation of the electron and hole density in a semiconductor

98

Calculation of the electron and hole density in a semiconductor

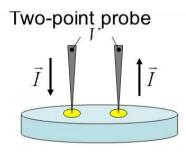




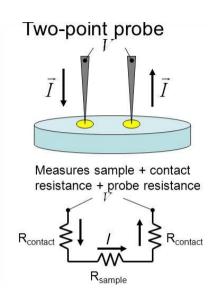
4-point probe measures the resistivity of any semiconductor

100

2-point probe measures sample, contact and probe resistance

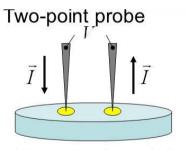


2-point probe measures sample, contact and probe resistance

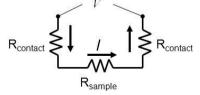


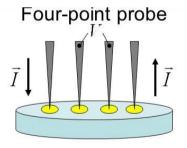
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4-point probe measures sample only

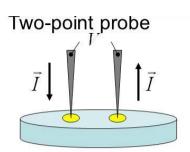


Measures sample + contact resistance + probe resistance



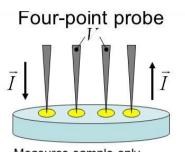


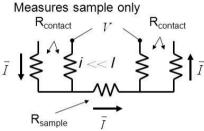
4-point probe measures sample only



Measures sample + contact resistance + probe resistance $R_{contact}$ $R_{contact}$ $R_{contact}$

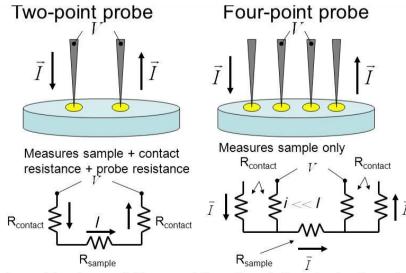
R_{sample}





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4-point probe measures sample only

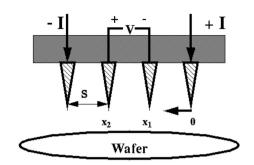


In four-point probe, negligible current flows through the voltmeter, the only voltage drop measured is across $\mathsf{R}_{\mathsf{sample}}.$

4-point probe method applies to bulk and thin films

- For bulk samples, thickness t >> s
- Assume spherical protrusion of current emanating from the outer probe tips
- The differential resistance is:

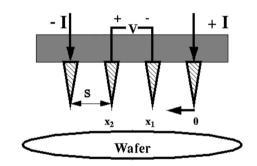
$$\Delta R = \rho\left(\frac{dx}{A}\right)$$



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4-point probe method applies to bulk and thin films

- Integration between the inner probe tips (where the voltage is measured)
- Assume spherical protrusion of current emanating from the outer probe tips



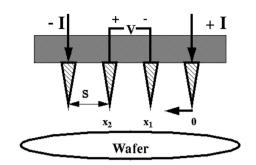
$$R = \int_{x_1}^{x_2} p \frac{dx}{2\pi x^2} = \frac{p}{2\pi} \left(-\frac{1}{x} \right) \Big|_{x_1}^{x_2} = \frac{1}{2s} \frac{p}{2\pi}$$

Half sphere

4-point probe method applies to bulk and thin films

- superposition of current at the outer two tips: R = V/2I
- · the expression for bulk resistivity

$$\rho = 2\pi s \left(\frac{V}{I}\right)$$



x₂

x₁

Wafer

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4-point probe method applies to bulk and thin films

- For thin layers with thickness t << s
- Current rings instead of spheres emanate from the outer probe tips

• The area is thus:
$$A = 2\pi x t$$

• The resistance is:

$$R = \int_{x_1}^{x_2} \rho \frac{dx}{2\pi xt} = \int_{s}^{2s} \frac{\rho}{2\pi t} \frac{dx}{x} = \frac{\rho}{2\pi t} ln(x) \Big|_{s}^{2s} = \frac{\rho}{2\pi t} ln^2$$

+ I

A

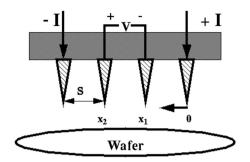
4-point probe method applies to bulk and thin films

 superposition of current at the outer two tips: R = V/2I

$$\rho = \frac{\pi t}{ln2} \left(\frac{V}{I} \right)$$

· Sheet resistivity is per thickness

$$R_{\rm s} = \rho/t = \frac{\pi}{\ln 2} \left(\frac{V}{I}\right)$$



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Final presentations are next M-W, any questions?

		characterization		
Week 10	M/W Group 1 final	T/Th Groups 1 & 2	M/W Group 2 final	No Lab
	presentations	final presentations	presentations	
3/9 -		No Lecture		No Lecture
3/12				
Week 11			M/W Groups	T/Th Groups
			semiconductor lab	semiconductor lab
3/14 -			reports due by 1 PM	reports due by 1 PM
3/20			PST	PST

References (see Class page)

Semiconductors

B. Van Zeghbroeck (2011) Principles of Semiconductors

 $https://ecee.colorado.edu/~bart/book/book/chapter2/ch2_6.htm\#fig2_6_5$

Four-point probe

Chan J Friedberg P (2002) Four point probe manual

Silicon wafer synthesis

Throughout